

# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
TO:	Please return this copy as a certification of your approval
Part No.:	Checked & Approved by:
Customer's Part No.:	Date:

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Part No.	:	SF7125
Pages	:	6
Date	:	2012/12/30
Revision	:	1.0



Prepared by:	
Checked by:	
Approved by:	

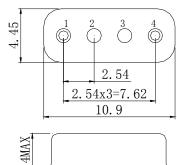
#### **Application**

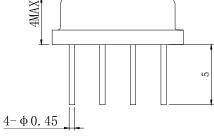
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 8 MHz

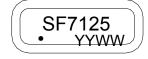
#### **Features**

- **RoHS** compatible
- Package size 10.9x4.45x4.00mm<sup>3</sup>
- Package Code SC04-06
- Electrostatic Sensitive Device(ESD)

#### Package Dimensions (Unit: mm)







# **Test Circuit**



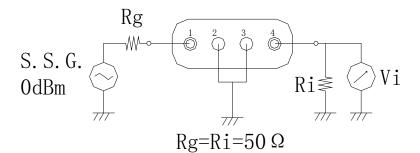
#### **Pin Configuration**

Pin No.	Description
1	Input
4	Output
2,3	Ground

# **Marking Description**

S	Trademark	
F	SAW Filter	
7125	Part Number	
•	Pin 1	
YYWW	Year Code & Week Code	

\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.



# **Performance**

#### **Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	Т	-40 ~ +85	${\mathbb C}$
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	${\mathbb C}$
RF Power Dissipation	Р	10	dBm

#### **Electronic Characteristics**

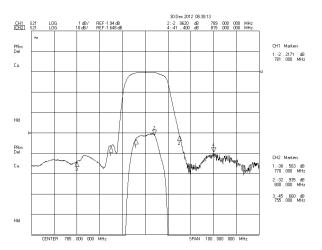
Test Temperature:  $25^{\circ}C \pm 2^{\circ}C$ 

Terminating source impedance:  $50\Omega$  Terminating load impedance:  $50\Omega$ 

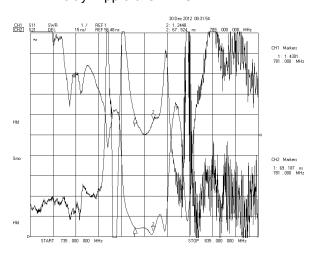
Item	Minimum	Typical	Maximum	Unit	
Center Frequency	fc		785.00		MHz
Insertion Loss(min)	IL		2.0	2.5	dB
Insertion Loss 781.00 - 789.00 MHz	IL		2.2	3.0	dB
Amplitude Ripple (p-p) 781.00 - 789.00 MHz	Δa		0.5	1.0	dB
Group Delay Ripple 781.00 - 789.00 MHz	GDR		15.0	40.0	ns
Absolute Attenuation	а				
DC - 700.00 MHz		50.0	55.0		dB
700.00 - 755.00 MHz		38.0	40.0		dB
770.00 MHz		30.0	35.0		dB
800.00 MHz		30.0	35.0		dB
815.00 - 1500.00 MHz		38.0	40.0		dB
1500.00 - 2000.00 MHz		30.0	35.0		dB
2000.00 - 2500.00 MHz		25.0	30.0		dB
2500.00 - 3000.00 MHz		15.0	18.0		dB
Input VSWR 781.00 - 789.00 MHz			1.8:1	2.0:1	/
Output VSWR 781.00 - 789.00 MHz			1.8:1	2.0:1	/

#### **Frequency Characteristics**

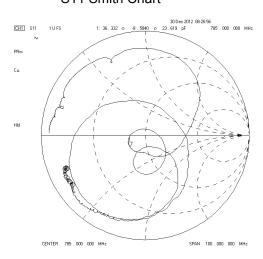
#### Frequency Response



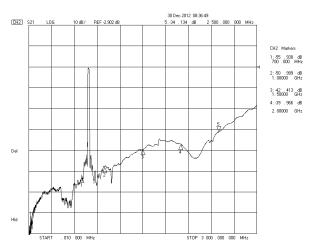
# Delay Ripple & S11 VSWR



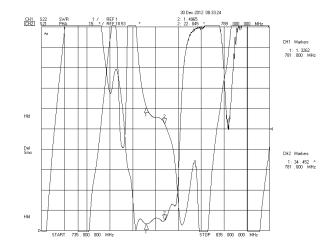
# S11 Smith Chart



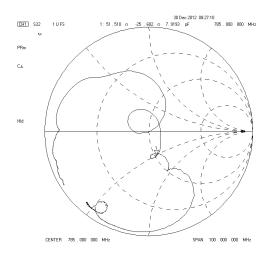
# Frequency Response (wideband)



# Phase Linearity & S22 VSWR



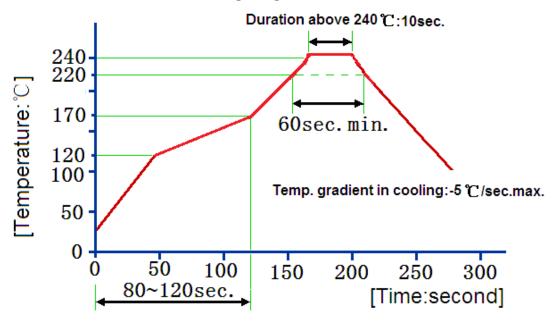
#### S22 Smith Chart



#### Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition	
1	Temperature	(1) Temperature: 85℃±2℃ , Duration: 250h , Recovery time: 2h±0.5h	
ļ	Storage	(2) Temperature: –55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60℃±2℃,90~95% RH	
3	Thormal Chook	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch	
3	Thermal Shock	time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
1	4 Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm	
_		Directions: X,Y and Z Duration: 2h	
5	Drop Test	Cycle time: 10 times Height: 1.0m	
	6 Solder Ability Test	Temperature: 245 ℃±5 ℃ Duration: 3.0s5.0s	
6		Depth: DIP2/3 , SMD1/5	
		(1)Thickness of PCB:1mm , Solder condition: 260 ℃±5 ℃ , Duration: 10±1s	
7	Resistance to Soldering Heat	(2)Temperature of Soldering Iron: 350℃±10℃,Duration: 3~4s,	
		Recovery time: 2 ± 0.5h	

# **Recommended Reflow Soldering Diagram**



Reflow cycles:3 cycles max.

785.00MHz SAW Filter SF7125 8MHz Bandwidth

#### **Notes**

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may be soldered. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.

Please read notes at the end of this document.